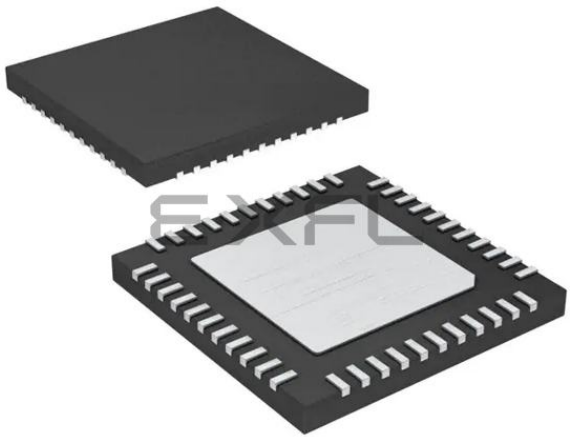

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I²S, Motor Control PWM, POR, PWM, WDT
Number of I/O	35
Program Memory Size	128KB (43K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 18x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep128gm304-e-ml

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Type	Buffer Type	PPS	Description
INDX1(1)	I	ST	Yes	Quadrature Encoder Index1 pulse input.
HOME1(1)	I	ST	Yes	Quadrature Encoder Home1 pulse input.
QEA1(1)	I	ST	Yes	Quadrature Encoder Phase A input in QEI1 mode. Auxiliary timer external clock input in Timer mode.
QEB1(1)	I	ST	Yes	Quadrature Encoder Phase A input in QEI1 mode. Auxiliary timer external gate input in Timer mode.
CNTCMP1(1)	O	—	Yes	Quadrature Encoder Compare Output 1.
INDX2(1)	I	ST	Yes	Quadrature Encoder Index2 Pulse input.
HOME2(1)	I	ST	Yes	Quadrature Encoder Home2 Pulse input.
QEA2(1)	I	ST	Yes	Quadrature Encoder Phase A input in QEI2 mode. Auxiliary timer external clock input in Timer mode.
QEB2(1)	I	ST	Yes	Quadrature Encoder Phase B input in QEI2 mode. Auxiliary timer external gate input in Timer mode.
CNTCMP2(1)	O	—	Yes	Quadrature Encoder Compare Output 2.
COFS	I/O	ST	Yes	Data Converter Interface frame synchronization pin.
CSCK	I/O	ST	Yes	Data Converter Interface serial clock input/output pin.
CSDI	I	ST	Yes	Data Converter Interface serial data input pin.
CSDO	O	—	Yes	Data Converter Interface serial data output pin.
C1RX	I	ST	Yes	CAN1 bus receive pin.
C1TX	O	—	Yes	CAN1 bus transmit pin
C2RX	I	ST	Yes	CAN2 bus receive pin.
C2TX	O	—	Yes	CAN2 bus transmit pin
RTCC	O	—	No	Real-Time Clock and Calendar alarm output.
CVREF	O	Analog	No	Comparator Voltage Reference output.
C1IN1+, C1IN2-, C1IN1-, C1IN3-	I	Analog	No	Comparator 1 inputs.
C1OUT	O	—	Yes	Comparator 1 output.
C2IN1+, C2IN2-, C2IN1-, C2IN3-	I	Analog	No	Comparator 2 inputs.
C2OUT	O	—	Yes	Comparator 2 output.
C3IN1+, C3IN2-, C2IN1-, C3IN3-	I	Analog	No	Comparator 3 inputs.
C3OUT	O	—	Yes	Comparator 3 output.
C4IN1+, C4IN2-, C4IN1-, C4IN3-	I	Analog	No	Comparator 4 inputs.
C4OUT	O	—	Yes	Comparator 4 output.
C5IN1-, C5IN2-, C5IN3-, C5IN4-, C5IN1+	I	Analog	No	Comparator 5 inputs.
C5OUT	O	—	Yes	Comparator 5 output.

Legend: CMOS = CMOS compatible input or output; Analog = Analog input; P = Power
ST = Schmitt Trigger input with CMOS levels; O = Output; I = Input
PPS = Peripheral Pin Select; TTL = TTL input buffer

Note 1: This pin is not available on all devices. For more information, see the **"Pin Diagrams"** section for pin availability.

2: AVDD must be connected at all times.

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3.6 CPU Control Registers

REGISTER 3-1: SR: CPU STATUS REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/C-0	R/C-0	R-0	R/W-0
OA	OB	SA(3)	SB(3)	OAB	SAB	DA	DC
bit 15							bit 8

R/W-0(2)	R/W-0(2)	R/W-0(2)	R-0	R/W-0	R/W-0	R/W-0	R/W-0
IPL2(1)	IPL1(1)	IPL0(1)	RA	N	OV	Z	C
bit 7							bit 0

Legend:	C = Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **OA:** Accumulator A Overflow Status bit
1 = Accumulator A has overflowed
0 = Accumulator A has not overflowed

bit 14 **OB:** Accumulator B Overflow Status bit
1 = Accumulator B has overflowed
0 = Accumulator B has not overflowed

bit 13 **SA:** Accumulator A Saturation 'Sticky' Status bit(3)
1 = Accumulator A is saturated or has been saturated at some time
0 = Accumulator A is not saturated

bit 12 **SB:** Accumulator B Saturation 'Sticky' Status bit(3)
1 = Accumulator B is saturated or has been saturated at some time
0 = Accumulator B is not saturated

bit 11 **OAB:** OA || OB Combined Accumulator Overflow Status bit
1 = Accumulator A or B has overflowed
0 = Neither Accumulator A or B has overflowed

bit 10 **SAB:** SA || SB Combined Accumulator 'Sticky' Status bit
1 = Accumulator A or B is saturated or has been saturated at some time
0 = Neither Accumulator A or B is saturated

bit 9 **DA:** DO Loop Active bit
1 = DO loop in progress
0 = DO loop not in progress

bit 8 **DC:** MCU ALU Half Carry/$\overline{\text{Borrow}}$ bit
1 = A carry-out from the 4th low-order bit (for byte-sized data) or 8th low-order bit (for word-sized data) of the result occurred
0 = No carry-out from the 4th low-order bit (for byte-sized data) or 8th low-order bit (for word-sized data) of the result occurred

Note 1: The IPL<2:0> bits are concatenated with the IPL<3> bit (CORCON<3>) to form the CPU Interrupt Priority Level. The value in parentheses indicates the IPL, if IPL<3> = 1. User interrupts are disabled when IPL<3> = 1.

2: The IPL<2:0> Status bits are read-only when the NSTDIS bit (INTCON1<15>) = 1.

3: A data write to the SR register can modify the SA and SB bits by either a data write to SA and SB or by clearing the SAB bit. To avoid a possible SA or SB bit write race condition, the SA and SB bits should not be modified using bit operations.

4.2 Data Address Space

The dsPIC33EPXXXGM3XX/6XX/7XX CPU has a separate 16-bit wide data memory space. The Data Space is accessed using separate Address Generation Units (AGUs) for read and write operations. The data memory maps, which are presented by device family and memory size, are shown in Figure 4-5 through Figure 4-7.

All Effective Addresses (EAs) in the data memory space are 16 bits wide and point to bytes within the Data Space. This arrangement gives a Base Data Space address range of 64 Kbytes or 32K words.

The Base Data Space address is used in conjunction with a Data Space Read or Write Page register (DSRPAG or DSWPAG) to form an Extended Data Space, which has a total address range of 16 Mbytes.

dsPIC33EPXXXGM3XX/6XX/7XX devices implement up to 52 Kbytes of data memory (4 Kbytes of data memory for Special Function Registers and up to 48 Kbytes of data memory for RAM). If an EA points to a location outside of this area, an all zero word or byte is returned.

4.2.1 DATA SPACE WIDTH

The data memory space is organized in byte-addressable, 16-bit wide blocks. Data is aligned in data memory and registers as 16-bit words, but all Data Space EAs resolve to bytes. The Least Significant Bytes (LSBs) of each word have even addresses, while the Most Significant Bytes (MSBs) have odd addresses.

4.2.2 DATA MEMORY ORGANIZATION AND ALIGNMENT

To maintain backward compatibility with PIC® MCU devices and improve Data Space memory usage efficiency, the dsPIC33EPXXXGM3XX/6XX/7XX instruction set supports both word and byte operations. As a consequence of byte accessibility, all Effective Address calculations are internally scaled to step through word-aligned memory. For example, the core recognizes that Post-Modified Register Indirect Addressing mode [Ws++] results in a value of Ws + 1 for byte operations and Ws + 2 for word operations.

A data byte read, reads the complete word that contains the byte, using the LSb of any EA to determine which byte to select. The selected byte is placed onto the LSB of the data path. That is, data memory and registers are organized as two parallel, byte-wide entities with shared (word) address decode but separate write lines. Data byte writes only write to the corresponding side of the array or register that matches the byte address.

All word accesses must be aligned to an even address. Misaligned word data fetches are not supported, so care must be taken when mixing byte and word operations, or translating from 8-bit MCU code. If a misaligned read or write is attempted, an address error trap is generated. If the error occurred on a read, the instruction underway is completed. If the error occurred on a write, the instruction is executed but the write does not occur. In either case, a trap is then executed, allowing the system and/or user application to examine the machine state prior to execution of the address Fault.

All byte loads into any W register are loaded into the LSB; the MSB is not modified.

A Sign-Extend (SE) instruction is provided to allow user applications to translate 8-bit signed data to 16-bit signed values. Alternatively, for 16-bit unsigned data, user applications can clear the MSB of any W register by executing a Zero-Extend (ZE) instruction on the appropriate address.

4.2.3 SFR SPACE

The first 4 Kbytes of the Near Data Space, from 0x0000 to 0x0FFF, is primarily occupied by Special Function Registers (SFRs). These are used by the dsPIC33EPXXXGM3XX/6XX/7XX core and peripheral modules for controlling the operation of the device.

SFRs are distributed among the modules that they control and are generally grouped together by module. Much of the SFR space contains unused addresses; these are read as '0'.

Note:	The actual set of peripheral features and interrupts varies by the device. Refer to the corresponding device tables and pinout diagrams for device-specific information.

4.2.4 NEAR DATA SPACE

The 8-Kbyte area, between 0x0000 and 0x1FFF, is referred to as the Near Data Space. Locations in this space are directly addressable through a 13-bit absolute address field within all memory direct instructions. Additionally, the whole Data Space is addressable using MOV instructions, which support Memory Direct Addressing mode with a 16-bit address field, or by using Indirect Addressing mode using a Working register as an Address Pointer.

TABLE 4-34: PERIPHERAL PIN SELECT INPUT REGISTER MAP FOR dsPIC33EPXXXGM3XX DEVICES

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
RPINR0	06A0	—	INT1R<6:0>							—	—	—	—	—	—	—	—	0000
RPINR1	06A2	—	—	—	—	—	—	—	—	—	INT2R<6:0>							0000
RPINR3	06A6	—	—	—	—	—	—	—	—	—	T2CKR<6:0>							0000
RPINR7	06AE	—	IC2R<6:0>							—	IC1R<6:0>							0000
RPINR8	06B0	—	IC4R<6:0>							—	IC3R<6:0>							0000
RPINR9	06B2	—	IC6R<6:0>							—	IC5R<6:0>							0000
RPINR10	06B4	—	IC8R<6:0>							—	IC7R<6:0>							0000
RPINR11	06B6	—	—	—	—	—	—	—	—	—	OCFAR<6:0>							0000
RPINR12	06B8	—	FLT2R<6:0>							—	FLT1R<6:0>							0000
RPINR14	06BC	—	QEB1R<6:0>							—	QEA1R<6:0>							0000
RPINR15	06BE	—	HOME1R<6:0>							—	INDX1R<6:0>							0000
RPINR16	06C0	—	QEB2R<6:0>							—	QEA2R<6:0>							0000
RPINR17	06C2	—	HOME2R<6:0>							—	INDX2R<6:0>							0000
RPINR18	06C4	—	—	—	—	—	—	—	—	—	U1RXR<6:0>							0000
RPINR19	06C6	—	—	—	—	—	—	—	—	—	U2RXR<6:0>							0000
RPINR22	06CC	—	SCK2R<6:0>							—	SDI2R<6:0>							0000
RPINR23	06CE	—	—	—	—	—	—	—	—	—	SS2R<6:0>							0000
RPINR24	06D0	—	CSCKR<6:0>							—	CSDIR<6:0>							0000
RPINR25	06D2	—	—	—	—	—	—	—	—	—	COFSR<6:0>							0000
RPINR27	06D6	—	U3CTSR<6:0>							—	U3RXR<6:0>							0000
RPINR28	06D8	—	U4CTSR<6:0>							—	U4RXR<6:0>							0000
RPINR29	06DA	—	SCK3R<6:0>							—	SDI3R<6:0>							0000
RPINR30	06DC	—	—	—	—	—	—	—	—	—	SS3R<6:0>							0000
RPINR37	06EA	—	SYNCI1R<6:0>							—	—	—	—	—	—	—	—	0000
RPINR38	06EC	—	DTCMP1R<6:0>							—	—	—	—	—	—	—	—	0000
RPINR39	06EE	—	DTCMP3R<6:0>							—	DTCMP2R<6:0>							0000
RPINR40	06F0	—	DTCMP5R<6:0>							—	DTCMP4R<6:0>							0000
RPINR41	06F2	—	—	—	—	—	—	—	—	—	DTCMP6R<6:0>							0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

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TABLE 4-42: CTMU REGISTER MAP

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
CTMUCON1	033A	CTMUEN	—	CTMUSIDL	TGEN	EDGEN	EDGSEQEN	IDISSEN	CTTRIG	—	—	—	—	—	—	—	—	0000
CTMUCON2	033C	EDG1MOD	EDG1POL	EDG1SEL3	EDG1SEL2	EDG1SEL1	EDG1SEL0	EDG2STAT	EDG1STAT	EDG2MOD	EDG2POL	EDG2SEL3	EDG2SEL2	EDG2SEL1	EDG2SEL0	—	—	0000
CTMUICON	033E	ITRIM5	ITRIM4	ITRIM3	ITRIM2	ITRIM1	ITRIM0	IRNG1	IRNG0	—	—	—	—	—	—	—	—	0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-43: JTAG INTERFACE REGISTER MAP

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
JDATAH	0FF0	—	—	—	—	JDATAH<27:16>												xxxx
JDATAL	0FF2	JDATAL<15:0>																0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-44: REAL-TIME CLOCK AND CALENDAR REGISTER MAP

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
ALRMVAL	0620	Alarm Value Register Window Based on ALRMPTR<1:0>																xxxx
ALCFGRPT	0622	ALRMEN	CHIME	AMASK3	AMASK2	AMASK1	AMASK0	ALRMPTR1	ALRMPTR0	ARPT7	ARPT6	ARPT5	ARPT4	ARPT3	ARPT2	ARPT1	ARPT0	0000
RTCVAL	0624	RTCC Value Register Window Based on RTCPTR<1:0>																xxxx
RCFGCAL	0626	RTCEN	—	RTCWREN	RTCSYNC	HALFSEC	RTCOE	RTCPTR1	RTCPTR0	CAL7	CAL6	CAL5	CAL4	CAL3	CAL2	CAL1	CAL0	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

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10.3 Doze Mode

The preferred strategies for reducing power consumption are changing clock speed and invoking one of the power-saving modes. In some circumstances, this cannot be practical. For example, it may be necessary for an application to maintain uninterrupted synchronous communication, even while it is doing nothing else. Reducing system clock speed can introduce communication errors, while using a power-saving mode can stop communications completely.

Doze mode is a simple and effective alternative method to reduce power consumption while the device is still executing code. In this mode, the system clock continues to operate from the same source and at the same speed. Peripheral modules continue to be clocked at the same speed, while the CPU clock speed is reduced. Synchronization between the two clock domains is maintained, allowing the peripherals to access the SFRs while the CPU executes code at a slower rate.

Doze mode is enabled by setting the DOZEN bit (CLKDIV<11>). The ratio between peripheral and core clock speed is determined by the DOZE<2:0> bits (CLKDIV<14:12>). There are eight possible configurations, from 1:1 to 1:128, with 1:1 being the default setting.

Programs can use Doze mode to selectively reduce power consumption in event-driven applications. This allows clock-sensitive functions, such as synchronous communications, to continue without interruption while the CPU Idles, waiting for something to invoke an interrupt routine. An automatic return to full-speed CPU operation on interrupts can be enabled by setting the ROI bit (CLKDIV<15>). By default, interrupt events have no effect on Doze mode operation.

For example, suppose the device is operating at 20 MIPS and the CAN module has been configured for 500 kbps based on this device operating speed. If the device is placed in Doze mode with a clock frequency ratio of 1:4, the CAN module continues to communicate at the required bit rate of 500 kbps, but the CPU now starts executing instructions at a frequency of 5 MIPS.

10.4 Peripheral Module Disable

The Peripheral Module Disable (PMD) registers provide a method to disable a peripheral module by stopping all clock sources supplied to that module. When a peripheral is disabled, using the appropriate PMD control bit, the peripheral is in a minimum power consumption state. The control and status registers associated with the peripheral are also disabled, so writes to those registers do not have effect and read values are invalid.

A peripheral module is enabled only if both the associated bit in the PMD register is cleared and the peripheral is supported by the specific dsPIC® DSC variant. If the peripheral is present in the device, it is enabled in the PMD register by default.

Note:	If a PMD bit is set, the corresponding module is disabled after a delay of one instruction cycle. Similarly, if a PMD bit is cleared, the corresponding module is enabled after a delay of one instruction cycle (assuming the module control registers are already configured to enable module operation).

REGISTER 11-29: RPINR41: PERIPHERAL PIN SELECT INPUT REGISTER 41

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	DTCMP6R<6:0>						
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-7 **Unimplemented:** Read as ‘0’

bit 6-0 **DTCMP6R<6:0>:** Assign PWM Dead-Time Compensation Input 6 to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

1111100 = Input tied to RPI124
•
•
•
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

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REGISTER 16-24: AUXCONx: PWMx AUXILIARY CONTROL REGISTER

U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	—	BLANKSEL3	BLANKSEL2	BLANKSEL1	BLANKSEL0
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	CHOPSEL3	CHOPSEL2	CHOPSEL1	CHOPSEL0	CHOPHEN	CHOPLEN
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-12 **Unimplemented:** Read as '0'

bit 11-8 **BLANKSEL<3:0>:** PWMx State Blank Source Select bits

The selected state blank signal will block the current-limit and/or Fault input signals (if enabled via the BCH and BCL bits in the LEBCONx register).

1001 = Reserved
•
•
•
0110 = PWM6H is selected as state blank source
0101 = PWM5H is selected as state blank source
0100 = PWM4H is selected as state blank source
0011 = PWM3H is selected as state blank source
0010 = PWM2H is selected as state blank source
0001 = PWM1H is selected as state blank source
0000 = No state blanking

bit 7-6 **Unimplemented:** Read as '0'

bit 5-2 **CHOPSEL<3:0>:** PWMx Chop Clock Source Select bits

The selected signal will enable and disable (CHOP) the selected PWMx outputs.

1001 = Reserved
•
•
•
0110 = PWM6H is selected as state blank source
0101 = PWM5H is selected as state blank source
0100 = PWM4H is selected as state blank source
0011 = PWM3H is selected as CHOP clock source
0010 = PWM2H is selected as CHOP clock source
0001 = PWM1H is selected as CHOP clock source
0000 = Chop clock generator is selected as CHOP clock source

bit 1 **CHOPHEN:** PWMxH Output Chopping Enable bit

1 = PWMxH chopping function is enabled
0 = PWMxH chopping function is disabled

bit 0 **CHOPLEN:** PWMxL Output Chopping Enable bit

1 = PWMxL chopping function is enabled
0 = PWMxL chopping function is disabled

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22.0 CHARGE TIME MEASUREMENT UNIT (CTMU)

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGM3XX/6XX/7XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the *"dsPIC33/PIC24 Family Reference Manual"*, **"Charge Time Measurement Unit (CTMU)"** (DS70661), which is available on the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The Charge Time Measurement Unit is a flexible analog module that provides accurate differential time measurement between pulse sources, as well as asynchronous pulse generation. Its key features include:

- Four edge input trigger sources
- Polarity control for each edge source
- Control of edge sequence
- Control of response to edges
- Precise time measurement resolution of 1 ns
- Accurate current source suitable for capacitive measurement
- On-chip temperature measurement using a built-in diode

Together with other on-chip analog modules, the CTMU can be used to precisely measure time, measure capacitance, measure relative changes in capacitance or generate output pulses that are independent of the system clock.

The CTMU module is ideal for interfacing with capacitive-based sensors. The CTMU is controlled through three registers: CTMUCON1, CTMUCON2 and CTMUICON. CTMUCON1 and CTMUCON2 enable the module and control edge source selection, edge source polarity selection and edge sequencing. The CTMUICON register controls the selection and trim of the current source.

REGISTER 25-3: PTGBTE: PTG BROADCAST TRIGGER ENABLE REGISTER(1,2) (CONTINUED)

bit 4 **OC1CS:** Clock Source for OC1 bit
1 = Generates clock pulse when the broadcast command is executed
0 = Does not generate clock pulse when the broadcast command is executed

bit 3 **OC4TSS:** Trigger/Synchronization Source for OC4 bit
1 = Generates trigger/synchronization when the broadcast command is executed
0 = Does not generate trigger/synchronization when the broadcast command is executed

bit 2 **OC3TSS:** Trigger/Synchronization Source for OC3 bit
1 = Generates trigger/synchronization when the broadcast command is executed
0 = Does not generate trigger/synchronization when the broadcast command is executed

bit 1 **OC2TSS:** Trigger/Synchronization Source for OC2 bit
1 = Generates trigger/synchronization when the broadcast command is executed
0 = Does not generate trigger/synchronization when the broadcast command is executed

bit 0 **OC1TSS:** Trigger/Synchronization Source for OC1 bit
1 = Generates trigger/synchronization when the broadcast command is executed
0 = Does not generate trigger/synchronization when the broadcast command is executed

Note 1: This register is read-only when the PTG module is executing Step commands (PTGEN = 1 and PTGSTRT = 1).

2: This register is only used with the PTGCTRL OPTION = 1111 Step command.

FIGURE 26-3: USER-PROGRAMMABLE BLANKING FUNCTION BLOCK DIAGRAM

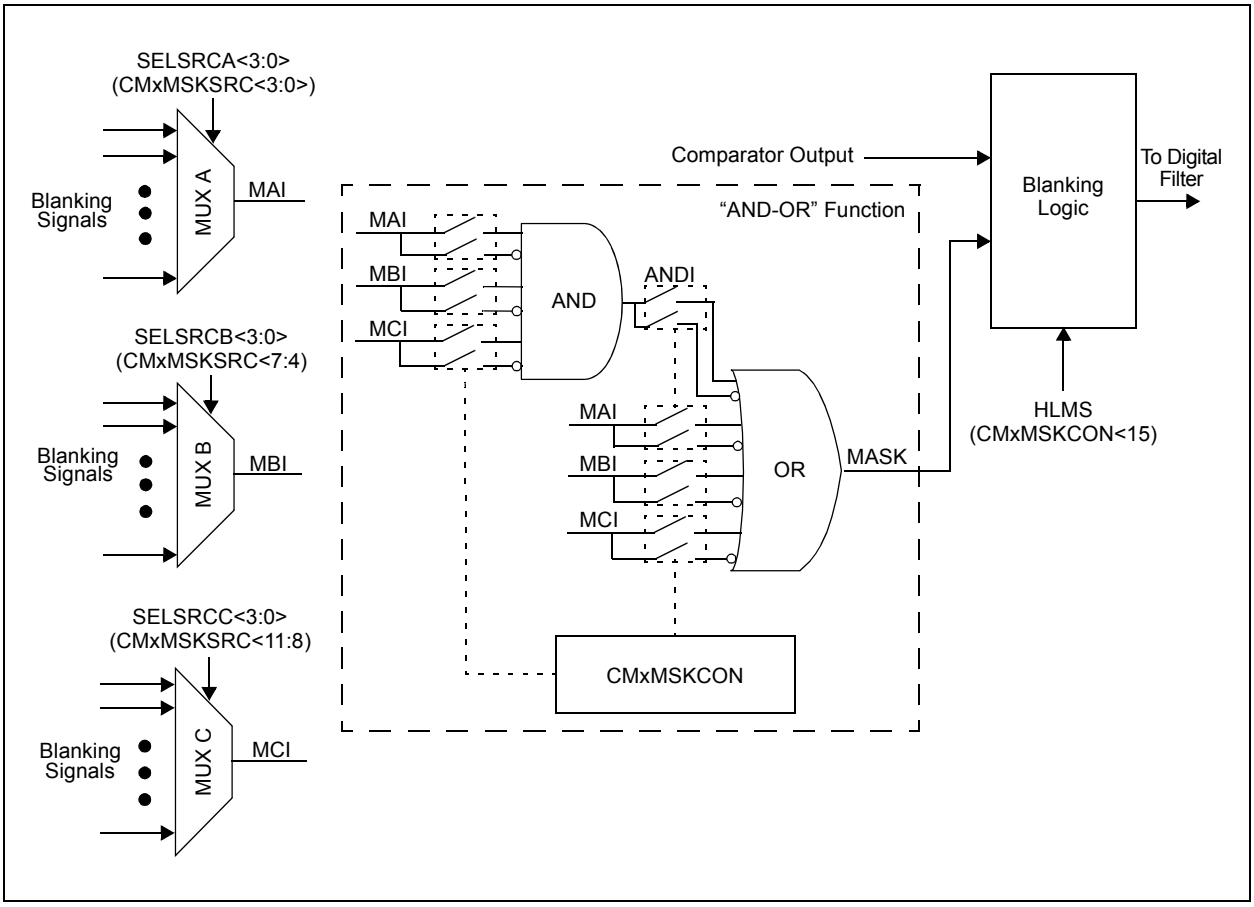
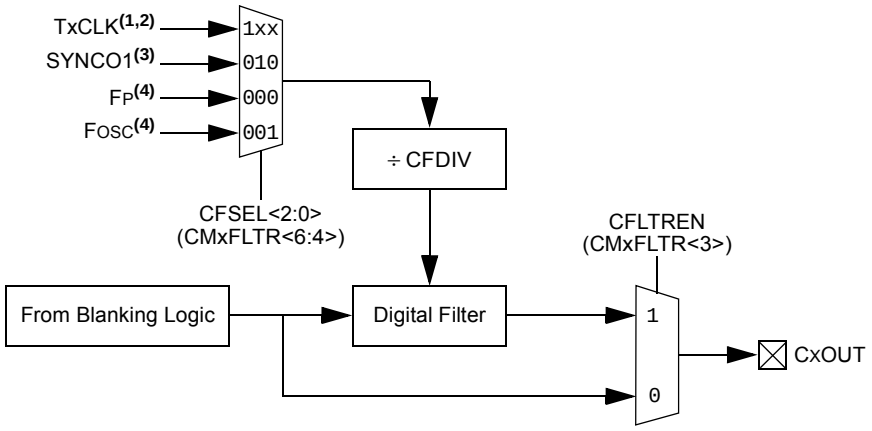


FIGURE 26-4: DIGITAL FILTER INTERCONNECT BLOCK DIAGRAM



Note 1: See the Type C Timer Block Diagram (Figure 13-2).
2: See the Type B Timer Block Diagram (Figure 13-1).
3: See the PWMx Module Register Interconnect Diagram (Figure 16-2).
4: See the Oscillator System Diagram (Figure 9-1).

REGISTER 27-3: ALCFGRPT: ALARM CONFIGURATION REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ALRMEN	CHIME	AMASK3	AMASK2	AMASK1	AMASK0	ALRMPTR1	ALRMPTR0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ARPT7	ARPT6	ARPT5	ARPT4	ARPT3	ARPT2	ARPT1	ARPT0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ALRMEN:** Alarm Enable bit

1 = Alarm is enabled (cleared automatically after an alarm event whenever ARPT<7:0> = 0x00 and CHIME = 0)
0 = Alarm is disabled

bit 14 **CHIME:** Chime Enable bit

1 = Chime is enabled; ARPT<7:0> bits are allowed to roll over from 0x00 to 0xFF
0 = Chime is disabled; ARPT<7:0> bits stop once they reach 0x00

bit 13-10 **AMASK<3:0>:** Alarm Mask Configuration bits

0000 = Every half second
0001 = Every second
0010 = Every 10 seconds
0011 = Every minute
0100 = Every 10 minutes
0101 = Every hour
0110 = Once a day
0111 = Once a week
1000 = Once a month
1001 = Once a year (except when configured for February 29th, once every 4 years)
101x = Reserved – do not use
11xx = Reserved – do not use

bit 9-8 **ALRMPTR<1:0>:** Alarm Value Register Window Pointer bits

Points to the corresponding Alarm Value registers when reading the ALRMVAL register. The ALRMPTR<1:0> value decrements on every read or write of ALRMVAL until it reaches '00'.

bit 7-0 **ARPT<7:0>:** Alarm Repeat Counter Value bits

11111111 = Alarm will repeat 255 more times
•
•
•
00000000 = Alarm will not repeat

The counter decrements on any alarm event. The counter is prevented from rolling over from 0x00 to 0xFF unless CHIME = 1.

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REGISTER 28-4: PMAEN: PARALLEL MASTER PORT ADDRESS ENABLE REGISTER(1)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PTEN15	PTEN14	PTEN<13:8>					
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PTEN<7:2>						PTEN<1:0>	
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at Reset	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **PTEN15:** PMCS2 Strobe Enable bit
1 = PMA15 functions as either PMA<15> or PMCS2
0 = PMA15 functions as port I/O

bit 14 **PTEN14:** PMCS1 Strobe Enable bit
1 = PMA14 functions as either PMA<14> or PMCS1
0 = PMA14 functions as port I/O

bit 13-2 **PTEN<13:2>:** PMP Address Port Enable bits
1 = PMA<13:2> function as PMP address lines
0 = PMA<13:2> function as port I/Os

bit 1-0 **PTEN<1:0>:** PMALH/PMALL Strobe Enable bits
1 = PMA1 and PMA0 function as either PMA<1:0> or PMALH and PMALL
0 = PMA1 and PMA0 function as port I/Os

Note 1: This register is not available on 44-pin devices.

TABLE 33-17: PLL CLOCK TIMING SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.(1)**	**Max.**	**Units**	**Conditions**
OS50	FPLLI	PLL Voltage Controlled Oscillator (VCO) Input Frequency Range	0.8	—	8.0	MHz	ECPLL, XTPLL modes
OS51	FSYS	On-Chip VCO System Frequency	120	—	340	MHz	
OS52	TLOCK	PLL Start-up Time (Lock Time)	0.9	1.5	3.1	ms	
OS53	DCLK	CLKO Stability (Jitter)(2)	-3	0.5	3	%	

Note 1: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: This jitter specification is based on clock cycle-by-clock cycle measurements. To get the effective jitter for individual time bases or communication clocks used by the application, use the following formula:

$$\text{Effective Jitter} = \frac{DCLK}{\sqrt{\frac{FOSC}{\text{Time Base or Communication Clock}}}}$$

For example, if FOSC = 120 MHz and the SPI bit rate = 10 MHz, the effective jitter is as follows:

$$\text{Effective Jitter} = \frac{DCLK}{\sqrt{\frac{120}{10}}} = \frac{DCLK}{\sqrt{12}} = \frac{DCLK}{3.464}$$

TABLE 33-18: INTERNAL FRC ACCURACY

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended					
Param No.	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**	
Internal FRC Accuracy @ FRC Frequency = 7.3728 MHz(1)							
F20a	FRC	-1.5	0.5	+1.5	%	-40°C ≤ TA ≤ +85°C	VDD = 3.0-3.6V
F20b	FRC	-2	1.5	+2	%	-40°C ≤ TA ≤ +125°C	VDD = 3.0-3.6V

Note 1: Frequency calibrated at +25°C and 3.3V. TUNx bits can be used to compensate for temperature drift.

TABLE 33-19: INTERNAL LPRC ACCURACY

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended					
Param No.	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**	
LPRC @ 32.768 kHz							
F21a	LPRC	-15	5	+15	%	-40°C ≤ TA ≤ +85°C	VDD = 3.0-3.6V
F21b	LPRC	-30	10	+30	%	-40°C ≤ TA ≤ +125°C	VDD = 3.0-3.6V

FIGURE 33-19: SPI2 AND SPI3 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 0, SMP = 0) TIMING CHARACTERISTICS

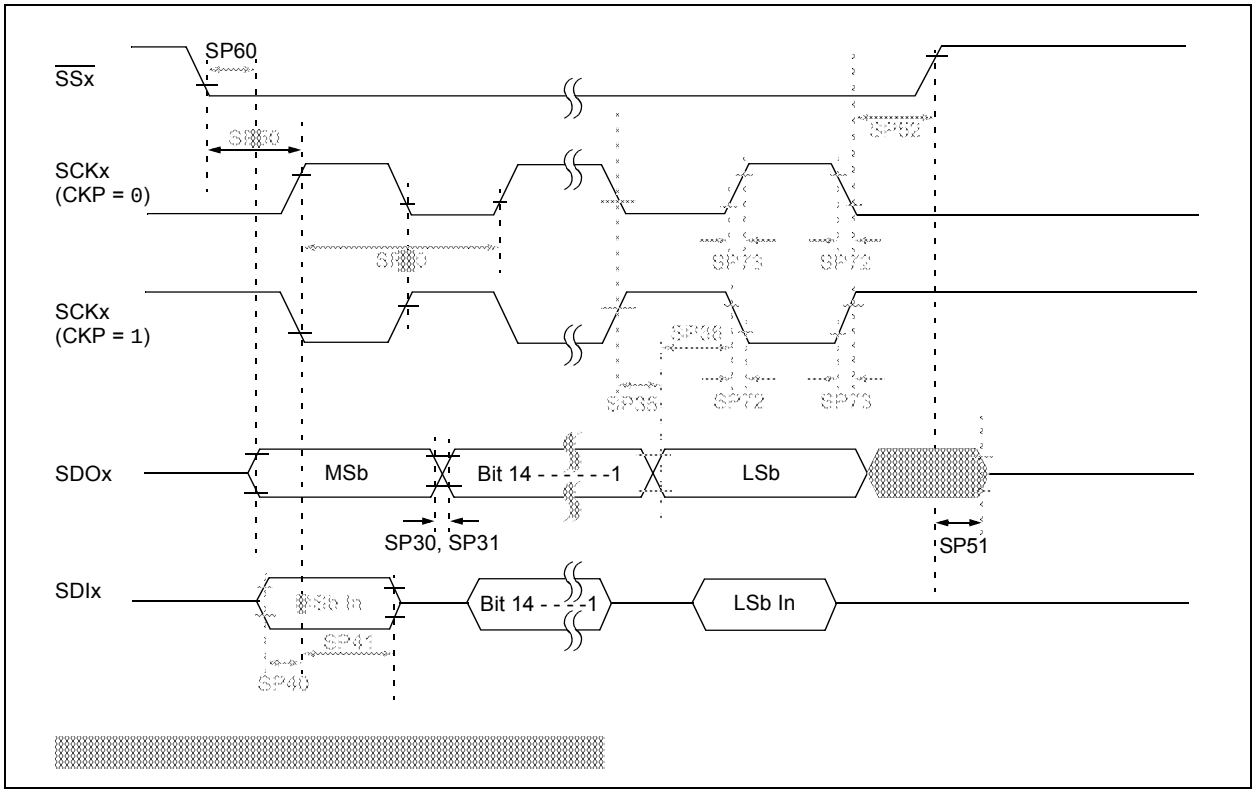

TABLE 33-38: SPI2 AND SPI3 SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 1, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCKx Input Frequency	—	—	15	MHz	**(Note 3)**
SP72	TscF	SCKx Input Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP73	TscR	SCKx Input Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SSx}$ ↓ to SCKx ↑ or SCKx ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SSx}$ ↑ to SDOx Output High-Impedance	10	—	50	ns	**(Note 4)**
SP52	TscH2ssH TscL2ssH	$\overline{SSx}$ ↑ after SCKx Edge	1.5 TCY + 40	—	—	ns	**(Note 4)**

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCKx is 66.7 ns. Therefore, the SCKx clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

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TABLE 34-11: PLL CLOCK TIMING SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C				
Param No.	Symbol	Characteristic	Min	Typ	Max	Units	Conditions
HOS53	DCLK	CLKO Stability (Jitter)(1)	-5	0.5	5	%	Measured over 100 ms period

Note 1: These parameters are characterized by similarity, but are not tested in manufacturing. This specification is based on clock cycle by clock cycle measurements. To calculate the effective jitter for individual time bases or communication clocks use this formula:

$$Peripheral\ Clock\ Jitter = \frac{DCLK}{\sqrt{\left(\frac{FOSC}{Peripheral\ Bit\ Rate\ Clock}\right)}}$$

For example: FOSC = 32 MHz, DCLK = 5%, SPIx bit rate clock (i.e., SCKx) is 2 MHz.

$$SPI\ SCK\ Jitter = \left\lfloor \frac{DCLK}{\sqrt{\left(\frac{32\ MHz}{2\ MHz}\right)}} \right\rfloor = \left\lfloor \frac{5\%}{\sqrt{16}} \right\rfloor = \left\lfloor \frac{5\%}{4} \right\rfloor = 1.25\%$$

TABLE 34-12: INTERNAL FRC ACCURACY

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C					
Param No.	Characteristic	Min	Typ	Max	Units	Conditions	
	Internal FRC Accuracy @ FRC Frequency = 7.3728 MHz						
HF20	FRC	-3	—	+3	%	-40°C ≤ TA ≤ +150°C	VDD = 3.0-3.6V

TABLE 34-13: INTERNAL RC ACCURACY

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C					
Param No.	Characteristic	Min	Typ	Max	Units	Conditions	
	LPRC @ 32.768 kHz(1,2)						
HF21	LPRC	-30	—	+30	%	-40°C ≤ TA ≤ +150°C	VDD = 3.0-3.6V

Note 1: Change of LPRC frequency as VDD changes.

2: LPRC accuracy impacts the Watchdog Timer Time-out Period (TWDT1). See **Section 30.5 "Watchdog Timer (WDT)"** for more information.

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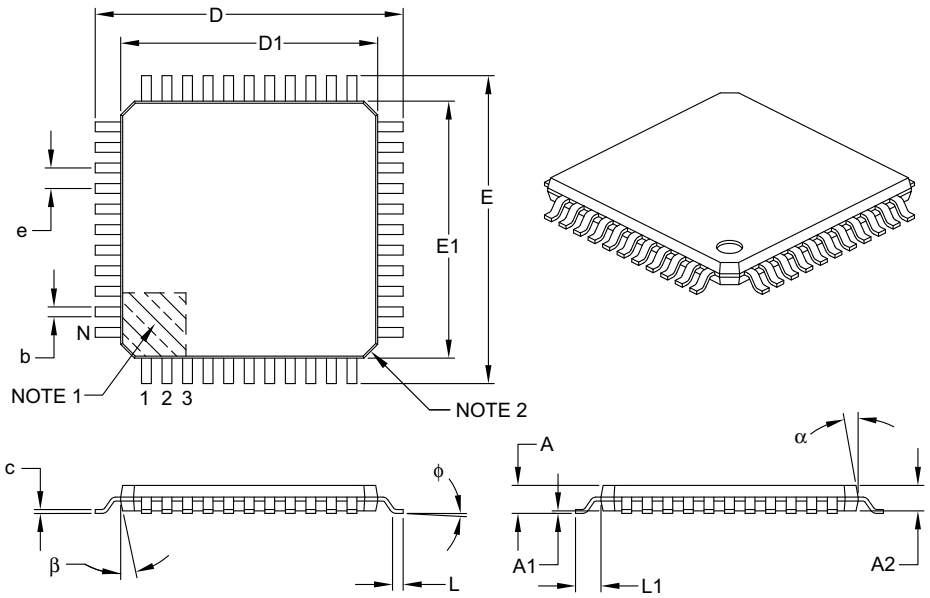
35.2 Package Details

44-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		44	
Lead Pitch	e		0.80 BSC	
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	φ	0°	3.5°	7°
Overall Width	E		12.00 BSC	
Overall Length	D		12.00 BSC	
Molded Package Width	E1		10.00 BSC	
Molded Package Length	D1		10.00 BSC	
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.30	0.37	0.45
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-076B

APPENDIX A: REVISION HISTORY

Revision A (February 2013)

This is the initial released version of this document.

Revision B (June 2013)

Changes to **Section 5.0 "Flash Program Memory"**, Register 5-1. Changes to **Section 6.0 "Resets"**, Figure 6-1. Changes to **Section 26.0 "Op Amp/Comparator Module"**, Register 26-2. Updates to most of the tables in **Section 33.0 "Electrical Characteristics"**. Minor text edits throughout the document.

Revision C (September 2013)

Changes to Figure 23-1. Changes to Figure 26-2. Changes to Table 30-2. Changes to **Section 33.0 "Electrical Characteristics"**. Added **Section 34.0 "High-Temperature Electrical Characteristics"** to the data sheet. Minor typographical edits throughout the document.

Revision D (August 2014)

This revision incorporates the following updates:

- Sections:
  - Updated **Section 2.0 "Guidelines for Getting Started with 16-Bit Digital Signal Controllers"**, **Section 8.0 "Direct Memory Access (DMA)"**, **Section 10.3 "Doze Mode"**, **Section 21.0 "Controller Area Network (CAN) Module (dsPIC33EPXXXGM6XX/7XX Devices Only)"**, **Section 23.0 "10-Bit/12-Bit Analog-to-Digital Converter (ADC)"**, **Section 23.1.2 "12-Bit ADCx Configuration"**, **Section 21.4 "CAN Message Buffers"**, **Section 35.0 "Packaging Information"**
- Figures:
  - Updated **"Pin Diagrams"**, Figure 1-1, Figure 9-1
- Registers:
  - Updated Register 5-1, Register 8-2, Register 21-1, Register 23-2
- Tables:
  - Updated Table 1-1, Table 7-1, Table 8-1, Table 34-9, Table 1, Table 4-2, Table 4-3, Table 4-25, Table 4-33, Table 4-34, Table 4-39, Table 4-30, Table 4-46, Table 4-47, Table 33-16,Table 34-8

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